

(19) United States

(12) Patent Application Publication (10) Pub. No.: US 2024/0213427 A1 HOSOKAWA et al.

Jun. 27, 2024 (43) **Pub. Date:**

(54) WIRING SUBSTRATE, LIGHT-EMITTING DEVICE, AND MANUFACTURING METHODS THEREOF

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Appl. No.: 18/389,775 (21)

(22)Filed: Dec. 20, 2023

(30)Foreign Application Priority Data

Dec. 21, 2022 (JP) 2022-204787

Publication Classification

(51) Int. Cl. H01L 33/62 (2006.01)H01L 33/52 (2006.01)H01L 33/60 (2006.01)

(52) U.S. Cl.

CPC *H01L 33/62* (2013.01); *H01L 33/52* (2013.01); H01L 33/60 (2013.01); H01L 24/16 (2013.01); H01L 2933/005 (2013.01); H01L 2933/0058 (2013.01); H01L 2933/0066 (2013.01)

(57)**ABSTRACT**

A wiring substrate including a base body provided with a via hole, a conductive portion disposed in the via hole, and a wiring portion electrically connected to the conductive portion and disposed on a surface of the body. The conductive portion includes a first conductive member containing copper particles and a resin. The first member contains smallsized particles with a particle size from 0.1 µm to 1.0 µm and large-sized particles with a particle size from more than 1.0 μm to 10 μm. The wiring portion includes a second conductive member containing copper particles. The second member contains small-sized particles with a particle size from 0.1 µm to 1.0 µm and large-sized particles with a particle size from more than 1.0 µm to 10 µm. A weight proportion of the small-sized particles in the first member is lower than a weight proportion of the small-sized particles in the second member.

